

L Number	Hits	Search Text	DB	Time stamp
1	5	heat adj sink with conductive adj insert	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:07
2	7	(257/720 and 165/104.33).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:09
3	26	(257/720).ccls. and heat adj pipe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:14
4	304	165/104.33.ccls. and thermal adj2 conductivity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:15
5	301	165/104.33.ccls. and thermal adj conductivity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:39
6	13	("5365749" "5549155" "5630469" "5647429" "5719745" "5734554" "5875095" "6018465" "6038128" "6054676" "6094346" "6125035" "6212074").PN.	USPAT	2004/06/01 02:25
7	18	("3586102" "4563725" "4833567" "5126919" "5168919" "5296739" "5323292" "5430611" "5508884" "5713690" "5754401" "5829512" "5831831" "5863814" "5880524" "5880930" "5932925" "5945217").PN.	USPAT	2004/06/01 02:26
8	10	("4675783" "5568360" "5598320" "5712762" "5764482" "5784256" "5822187" "5826645" "5910883" "5966286").PN.	USPAT	2004/06/01 02:29
9	2420	heat adj pipe same heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:40
10	816	heat adj pipe same cooling with (IC or chip or component)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:40